

Instruction Manual



TMS 161 80960Cx Microprocessor Support 070-9816-00

There are no current European directives that apply to this product. This product provides cable and test lead connections to a test object of electronic measuring and test equipment.

Warning

The servicing instructions are for use by qualified personnel only. To avoid personal injury, do not perform any servicing unless you are qualified to do so. Refer to all safety summaries prior to performing service.

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Table of Contents

General Safety Summary	v
Service Safety Summary	vii
Preface: Microprocessor Support Documentation	ix
Manual Conventions	ix
Logic Analyzer Documentation	x
Contacting Tektronix	x

Getting Started

Getting Started	1-1
Support Description	1-1
Logic Analyzer Software Compatibility	1-2
Logic Analyzer Configuration	1-2
Requirements and Restrictions	1-2
Configuring the Probe Adapter	1-3
Connecting to a System Under Test	1-5
PGA Probe Adapter	1-5
Without a Probe Adapter	1-8

Operating Basics

Setting Up the Support	2-1
Channel Group Definitions	2-1
Clocking Options	2-1
Symbols	2-2
Acquiring and Viewing Disassembled Data	2-7
Acquiring Data	2-7
Viewing Disassembled Data	2-7
Hardware Display Format	2-8
Software Display Format	2-9
Control Flow Display Format	2-10
Subroutine Display Format	2-11
Changing How Data is Displayed	2-11
Optional Display Selections	2-11
Burst or Burst Pipelining Mode Addressing	2-12
A0 and A1 Signals	2-12
Marking Cycles	2-13
Viewing an Example of Disassembled Data	2-13

Specifications

Specifications	3-1
Probe Adapter Description	3-1
Configuring the Probe Adapter	3-1
Specifications	3-2
Channel Assignments	3-5
How Data is Acquired	3-11
Custom Clocking	3-11
Clocking Options	3-13
Synthesized Signals	3-13
Alternate Microprocessor Connections	3-14
Signals On the Probe Adapter	3-14
Extra Channels	3-14

Maintenance

Maintenance	4-1
Probe Adapter Circuit Description	4-1
Replacing Signal Leads	4-2
Replacing Protective Sockets	4-2

Replaceable Electrical Parts

Replaceable Electrical Parts	5-1
Parts Ordering Information	5-1
Using the Replaceable Electrical Parts List	5-1

Replaceable Mechanical Parts

Replaceable Mechanical Parts	6-1
Parts Ordering Information	6-1
Using the Replaceable Mechanical Parts List	6-1

Index

List of Figures

Figure 1–1: Location of the DIP switches on the probe adapter	1–4
Figure 1–2: Placing the microprocessor into the ZIF socket	1–6
Figure 1–3: Connecting the probes to the probe adapter	1–7
Figure 1–4: Placing the probe adapter onto the SUT	1–8
Figure 2–1: Hardware display format	2–9
Figure 3–1: Minimum clearance of the standard probe adapter	3–5
Figure 3–2: 80960Cx bus timing	3–12
Figure 6–1: Exploded view of probe adapter	6–5

List of Tables

Table 1–1: Region table entry and DIP switch settings	1–4
Table 1–2: Address region and DIP switch assignments	1–5
Table 1–3: 80960Cx signal connections for channel probes	1–9
Table 1–4: 80960Cx signal connections for clock probes	1–10
Table 2–1: Control group symbol table definitions	2–2
Table 2–2: Intr Group symbol table, dedicated mode*	2–3
Table 2–3: Misc group symbol table definitions	2–3
Table 2–4: Initialization boot record (IBR) symbol table	2–4
Table 2–5: Process control block (PRCB) symbol table	2–4
Table 2–6: System procedure table symbol table	2–5
Table 2–7: Interrupt Table symbol table	2–5
Table 2–8: Fault Table symbol table	2–5
Table 2–9: Control Table symbol table*	2–6
Table 2–10: Special characters in the display and meaning	2–8
Table 2–11: Cycle type definitions	2–8
Table 2–12: Triggering on specific addresses	2–12
Table 3–1: Electrical specifications	3–2
Table 3–2: Environmental specifications[.....	3–4
Table 3–3: Certifications and compliances	3–4
Table 3–4: Address group channel assignments	3–6
Table 3–5: Data group channel assignments	3–7
Table 3–6: Control group channel assignments	3–8
Table 3–7: DataSize group channel assignments	3–9
Table 3–8: Intr group channel assignments	3–9
Table 3–9: Misc group channel assignments	3–10
Table 3–10: Clock channel assignments	3–10
Table 3–11: Synthesized signals	3–14
Table 3–12: Extra module sections and channels	3–14

General Safety Summary

Review the following safety precautions to avoid injury and prevent damage to this product or any products connected to it. To avoid potential hazards, use this product only as specified.

Only qualified personnel should perform service procedures.

While using this product, you may need to access other parts of the system. Read the *General Safety Summary* in other system manuals for warnings and cautions related to operating the system.

To Avoid Fire or Personal Injury

Connect and Disconnect Properly. Do not connect or disconnect probes or test leads while they are connected to a voltage source.

Observe All Terminal Ratings. To avoid fire or shock hazard, observe all ratings and marking on the product. Consult the product manual for further ratings information before making connections to the product.

Do not apply a potential to any terminal, including the common terminal, that exceeds the maximum rating of that terminal.

Do Not Operate Without Covers. Do not operate this product with covers or panels removed.

Avoid Exposed Circuitry. Do not touch exposed connections and components when power is present.

Do Not Operate With Suspected Failures. If you suspect there is damage to this product, have it inspected by qualified service personnel.

Do Not Operate in Wet/Damp Conditions.

Do Not Operate in an Explosive Atmosphere.

Keep Product Surfaces Clean and Dry.

Provide Proper Ventilation. Refer to the manual's installation instructions for details on installing the product so it has proper ventilation.

Symbols and Terms

Terms in this Manual. These terms may appear in this manual:



WARNING. Warning statements identify conditions or practices that could result in injury or loss of life.



CAUTION. *Caution statements identify conditions or practices that could result in damage to this product or other property.*

Terms on the Product. These terms may appear on the product:

DANGER indicates an injury hazard immediately accessible as you read the marking.

WARNING indicates an injury hazard not immediately accessible as you read the marking.

CAUTION indicates a hazard to property including the product.

Symbols on the Product. The following symbols may appear on the product:



WARNING
High Voltage



Protective Ground
(Earth) Terminal



CAUTION
Refer to Manual



Double
Insulated

Service Safety Summary

Only qualified personnel should perform service procedures. Read this *Service Safety Summary* and the *General Safety Summary* before performing any service procedures.

Do Not Service Alone. Do not perform internal service or adjustments of this product unless another person capable of rendering first aid and resuscitation is present.

Disconnect Power. To avoid electric shock, disconnect the main power by means of the power cord or, if provided, the power switch.

Use Care When Servicing With Power On. Dangerous voltages or currents may exist in this product. Disconnect power, remove battery (if applicable), and disconnect test leads before removing protective panels, soldering, or replacing components.

To avoid electric shock, do not touch exposed connections.

Preface: Microprocessor Support Documentation

This instruction manual contains specific information about the TMS 161 80960Cx microprocessor support and is part of a set of information on how to operate this product on compatible Tektronix logic analyzers.

If you are familiar with operating microprocessor supports on the logic analyzer for which the TMS 161 80960Cx support was purchased, you will probably only need this instruction manual to set up and run the support.

If you are not familiar with operating microprocessor supports, you will need to supplement this instruction manual with information on basic operations to set up and run the support.

Information on basic operations of microprocessor supports is included with each product. Each logic analyzer has basic information that describes how to perform tasks common to supports on that platform. This information can be in the form of online help, an installation manual, or a user manual.

This manual provides detailed information on the following topics:

- Connecting the logic analyzer to the system under test
- Setting up the logic analyzer to acquire data from the system under test
- Acquiring and viewing disassembled data
- Using the probe adapter

Manual Conventions

This manual uses the following conventions:

- The term disassembler refers to the software that disassembles bus cycles into instruction mnemonics and cycle types.
- The phrase “information on basic operations” refers to online help, an installation manual, or a basic operations of microprocessor supports user manual.
- In the information on basic operations, the term XXX or 68340 used in field selections and file names can be replaced with 960CA. This is the name of the microprocessor in field selections and file names you must use to operate the 80960Cx support.
- The term system under test (SUT) refers to the microprocessor-based system from which data will be acquired.

- The term logic analyzer refers to the Tektronix logic analyzer for which this product was purchased.
- The term module refers to a 102/136-channel or 96-channel module.
- A pound sign (#) following a signal name indicates an active low signal.

Logic Analyzer Documentation

A description of other documentation available for each type of Tektronix logic analyzer is located in the corresponding module user manual. The manual set provides the information necessary to install, operate, maintain, and service the logic analyzer and associated products.

Contacting Tektronix

Product Support	For application-oriented questions about a Tektronix measurement product, call toll free in North America: 1-800-TEK-WIDE (1-800-835-9433 ext. 2440) 6:00 a.m. – 5:00 p.m. Pacific time Or, contact us by e-mail: tm_app_supp@tek.com For product support outside of North America, contact your local Tektronix distributor or sales office.
Service Support	Contact your local Tektronix distributor or sales office. Or, visit our web site for a listing of worldwide service locations. http://www.tek.com
For other information	In North America: 1-800-TEK-WIDE (1-800-835-9433) An operator will direct your call.
To write us	Tektronix, Inc. P.O. Box 1000 Wilsonville, OR 97070-1000



Getting Started

Getting Started

This chapter provides information on the following topics:

- A description of the TMS 161 microprocessor support
- Logic analyzer software compatibility
- Your system under test requirements
- Support restrictions
- How to configure the probe adapter
- How to connect to the system under test (SUT)

Support Description

The 80960Cx microprocessor support disassembles data from systems that are based on the Intel, Inc. 80960Cx microprocessor. The support runs on a compatible Tektronix logic analyzer equipped with a 102/136-channel module or a 96-channel module.

Refer to information on basic operations to determine how many modules and probes your logic analyzer needs to meet the minimum channel requirements for the 80960Cx microprocessor support.

The TMS 161 supports the 80960Cx microprocessor in a 168-pin PGA package.

A complete list of standard and optional accessories is provided at the end of the parts list in the *Replaceable Mechanical Parts* chapter.

To use this support efficiently, you need to have the items listed in the information on basic operations as well as the following documents:

- *80960CA 32-Bit High Performance Embedded Processor Data Sheet*, Intel, 270727-001, September 1989
- *80960CA User's Manual*, Intel, 270710-001, 1989
- *80960CA User's Manual Errata Revision 2.0*, Intel, December 19, 1989.

Information on basic operations also contains a general description of supports.

Logic Analyzer Software Compatibility

The label on the microprocessor support floppy disk states which version of logic analyzer software the support is compatible with.

Logic Analyzer Configuration

To use the 80960Cx support, the Tektronix logic analyzer must be equipped with either a 102/136-channel module, or a 96-channel module at a minimum. The module must be equipped with enough probes to acquire clock and channel data from signals in your 80960Cx-based system.

Refer to information on basic operations to determine how many modules and probes the logic analyzer needs to meet the channel requirements.

Requirements and Restrictions

You should review the general requirements and restrictions of microprocessor supports in the information on basic operations as they pertain to your SUT.

You should also review electrical, environmental, and mechanical specifications in the *Specifications* chapter in this manual as they pertain to your system under test, as well as the following descriptions of other 80960Cx support requirements and restrictions.

System Clock Rate. The microprocessor support product supports the 80960Cx microprocessor at speeds of up to 33 MHz¹.

Burst Mode Limitations. The 80960Cx microprocessor increments only the lower two address bits in burst mode, and the TMS 161 latches only the initial address and BE#3–BE#0, which allows the logic analyzer to acquire data at a speed for both the pipeline and burst mode.

Little-Endian Byte Ordering. The disassembler always uses Little-Endian byte ordering for instruction disassembly. Little-Endian byte ordering is when the least significant data byte is located at the lowest address.

Disabling the Instruction Cache. You must disable the internal instruction cache. Disabling the cache makes most instructions visible on the bus so the logic analyzer can acquire and display them.

¹ Specification at time of printing. Contact your Tektronix sales representative for current information on the fastest devices supported.

The disassembler might display flushed cycles for cycles that are not flushed when the 80960Cx internal instruction cache is in use. With the instruction cache turned on, the logic analyzer is only able to capture the instruction accesses that do not reside in the internal cache. It is difficult for the disassembler to decipher program execution when only a few instructions are visible.

Some instructions still might not appear in tight loops because the 80960Cx microprocessor has a cache prefetch queue (16 words deep), which is separate from the internal instruction cache and cannot be disabled. This might change with later versions of the 80960Cx microprocessor. Contact Intel if you have questions regarding the behavior of the various versions of the microprocessor.

Hardware Reset. If a hardware reset occurs in your 80960Cx system during an acquisition, the disassembler might acquire an invalid sample.

Probe Adapter Loading. Any electrical connection to your system adds an additional AC and DC load. The probe adapter was carefully designed to add a minimum load to your system. However, this additional load may affect the operation of the 80960Cx microprocessor in systems with extremely tight timing margins. The *Specifications* chapter contains complete specifications on how the probe adapter affects your system.

Intel states that they will not guarantee that the 25 MHz and 33 MHz versions of the 80960Cx will function properly with more than one protective socket installed in the 80960Cx system. The probe adapter contains one ZIF socket and two protective sockets. If loading from these sockets is a problem, remove the ZIF socket first. If loading is still a problem, you can remove the protective sockets from the underside of the probe adapter. Refer to the discussion on *Removing and Replacing Sockets* in the information on basic operations for instructions.

Configuring the Probe Adapter

The 80960Cx microprocessor uses the high-order four address lines to define 16 memory regions. The characteristics of each region is set up by software at power-up. You must set the DIP switches on the probe adapter to match the software settings of the “ready” mask for each memory region.

All the switches are open when the probe adapter is shipped; READY# is always monitored in all the memory regions until you change the settings. Figure 1–1 shows the location of the DIP switches on the probe adapter.

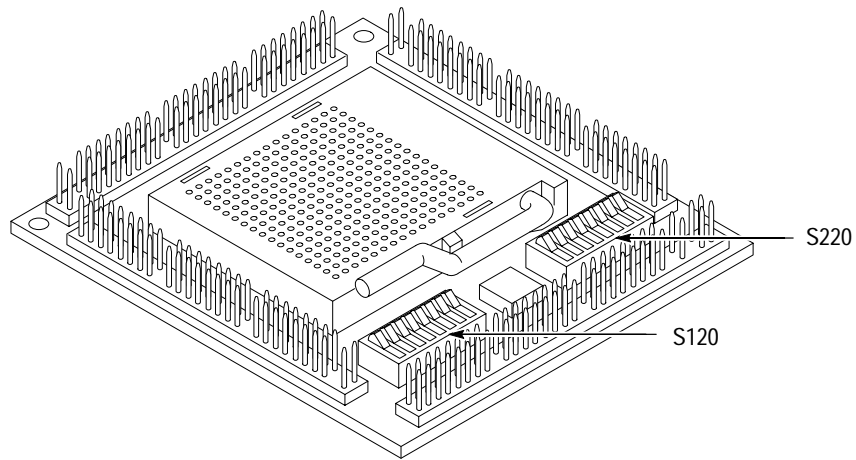


Figure 1-1: Location of the DIP switches on the probe adapter

To configure the probe adapter, follow these steps:

1. Determine how the 80960Cx system is configured in each of its regions. Compare the lower three bits for each region to the bit values in Table 1-1 to determine how to set the DIP switch on the probe adapter.

Table 1-1: Region table entry and DIP switch settings

Pipeline Enable bit 2	READY Enable bit 1	Burst Enable bit 0	DIP switch setting	Definition
0	0	0	Closed	Normal cycles only; READY# input is disabled
0	0	1	Closed	Burst cycles enabled; READY# and BTERM# inputs are disabled
0	1	0	Open	Normal cycles only; READY# input is enabled
0	1	1	Open	Burst cycles enabled; READY# and BTERM# inputs are enabled
1	0	0	Closed	Pipelined read cycles enabled, normal write cycles; READY# input is disabled
1	0	1	Closed	Pipelined burst read cycles enabled. Burst write cycles enabled. READY# and BTERM# inputs are disabled
1	1	0	Open	READY# input ignored for reads, valid for writes
1	1	1	Closed	READY# input ignored (illegal state)

2. Use Table 1-2 to determine which DIP switch to set for each memory region.

Table 1–2: Address region and DIP switch assignments

Address region (A31-A28)	Switch	Address region (A31-A28)	Switch
5 (1111)	S120-F	7 (0111)	S220-7
4 (1110)	S120-E	6 (0110)	S220-6
3 (1101)	S120-D	5 (0101)	S220-5
2 (1100)	S120-C	4 (0100)	S220-4
1 (1011)	S120-B	3 (0011)	S220-3
0 (1010)	S120-A	2 (0010)	S220-2
9 (1001)	S120-9	1 (0001)	S220-1
8 (1000)	S120-8	0 (0000)	S220-0

Connecting to a System Under Test

Before you connect to the SUT, you must connect the probes to the module. Your SUT must also have a minimum amount of clear space surrounding the microprocessor to accommodate the probe adapter. Refer to the *Specifications* chapter in this manual for the required clearances.

The channel and clock probes shown in this chapter are for a 102/136-channel module. The probes will look different if you are using a 96-channel module.

The general requirements and restrictions of microprocessor supports in the information on basic operations shows the vertical dimensions of a channel or clock probe connected to square pins on a circuit board.

PGA Probe Adapter

To connect the logic analyzer to the SUT, follow these steps:

1. Turn off power to your SUT. It is not necessary to turn off power to the logic analyzer.



CAUTION. Static discharge can damage the microprocessor, the probe adapter, the podlets, or the Module. To prevent static damage, handle all of the above only in a static-free environment.

Always wear a grounding wrist strap or similar device while handling the microprocessor and probe adapter.

2. To discharge your stored static electricity, touch the ground connector located on the back of the logic analyzer. Then, touch any of the ground pins of the probe adapter to discharge stored static electricity from the probe adapter.

NOTE. If your SUT has a ZIF socket with a lever attached, you might need to remove the protective socket from the bottom of the probe adapter, place it in your system's ZIF socket and then close the ZIF socket. Refer to information on basic operations for a description of how to remove protective socket from the probe adapter.

3. Place the probe adapter onto the antistatic shipping foam to support the probe as shown in Figure 1–2. This prevents the circuit board from flexing and the socket pins from bending.
4. Remove the 80960Cx microprocessor from your SUT.
5. Open the ZIF socket on the probe adapter (pull the lever up and away from the socket).
6. Line up the pin A1 indicator on the probe adapter board with the pin A1 indicator on the microprocessor.



CAUTION. Failure to correctly place the microprocessor into the probe adapter may permanently damage the microprocessor once power is applied.

7. Lock the ZIF socket in the closed position (push the lever down).
8. Place the microprocessor into the ZIF socket as shown in Figure 1–2.

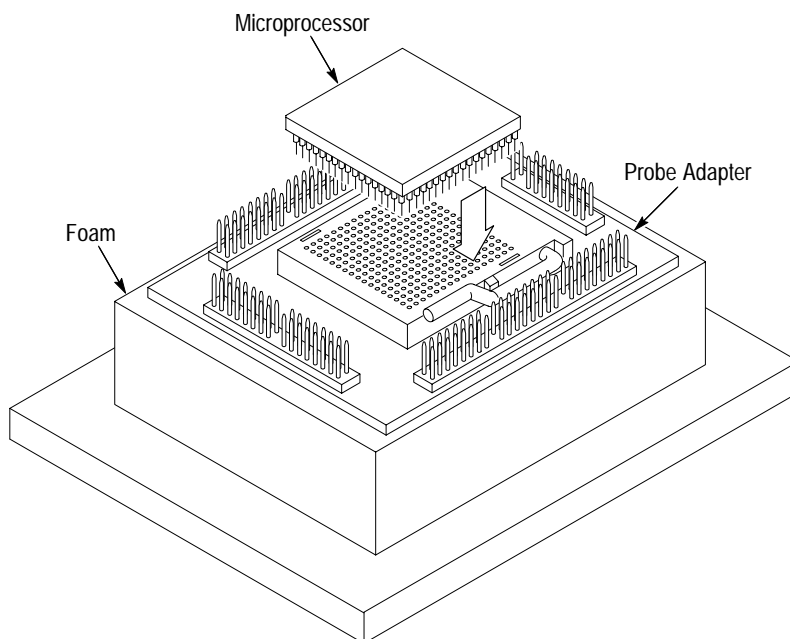


Figure 1–2: Placing the microprocessor into the ZIF socket

9. Connect the clock and 8-channel probes to the probe adapter as shown in Figure 1–3. Match the channel groups and numbers on the probe labels to the corresponding pins on the probe adapter.

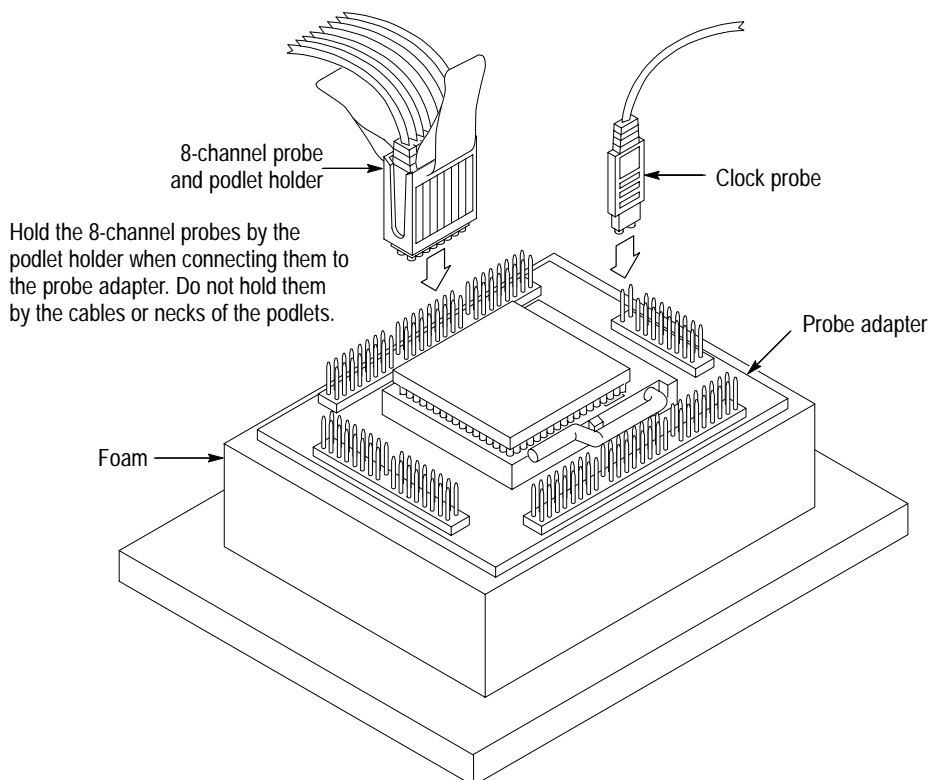


Figure 1–3: Connecting the probes to the probe adapter

10. Line up the pin A1 indicator on the probe adapter board with the pin A1 indicator on your SUT.
11. Place the probe adapter onto the SUT as shown in Figure 1–4.

NOTE. You may need to stack one or more replacement sockets between the SUT and the probe adapter to provide sufficient vertical clearance from adjacent components. However, keep in mind that this may increase loading, which can reduce the electrical performance of your probe adapter.

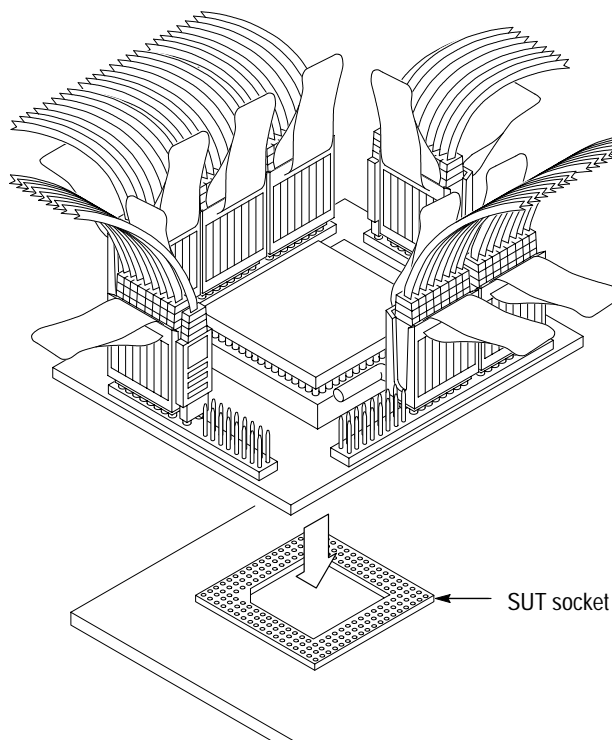


Figure 1-4: Placing the probe adapter onto the SUT

Without a Probe Adapter

You can use channel probes, clock probes, and leadsets with a commercial test clip (or adapter) to make connections between the logic analyzer and your SUT.

To connect the probes to 80960Cx signals in the SUT using a test clip, follow these steps:

1. Turn off power to your SUT. It is not necessary to turn off power to the logic analyzer.



CAUTION. Static discharge can damage the microprocessor, the probes, or the module. To prevent static damage, handle all of the above only in a static-free environment.

Always wear a grounding wrist strap or similar device while handling the microprocessor.

2. To discharge your stored static electricity, touch the ground connector located on the back of the logic analyzer. If you are using a test clip, touch any of the ground pins on the clip to discharge stored static electricity from it.

3. Use Table 1–3 to connect the channel probes to 80960Cx signal pins on the test clip or in the SUT.

Use leadsets to connect at least one ground lead from each channel probe and the ground lead from each clock probe to ground pins on your test clip.

Table 1–3: 80960Cx signal connections for channel probes

Section:channel	80960Cx signal	Section:channel	80960Cx signal
A3:7	A31	D3:7	D31
A3:6	A30	D3:6	D30
A3:5	A29	D3:5	D29
A3:4	A28	D3:4	D28
A3:3	A27	D3:3	D27
A3:2	A26	D3:2	D26
A3:1	A25	D3:1	D25
A3:0	A24	D3:0	D24
A2:7	A23	D2:7	D23
A2:6	A22	D2:6	D22
A2:5	A21	D2:5	D21
A2:4	A20	D2:4	D20
A2:3	A19	D2:3	D19
A2:2	A18	D2:2	D18
A2:1	A17	D2:1	D17
A2:0	A16	D2:0	D16
A1:7	A15	D1:7	D15
A1:6	A14	D1:6	D14
A1:5	A13	D1:5	D13
A1:4	A12	D1:4	D12
A1:3	A11	D1:3	D11
A1:2	A10	D1:2	D10
A1:1	A9	D1:1	D9
A1:0	A8	D1:0	D8
A0:7	A7	D0:7	D7
A0:6	A6	D0:6	D6
A0:5	A5	D0:5	D5
A0:4	A4	D0:4	D4
A0:3	A3	D0:3	D3
A0:2	A2	D0:2	D2
A0:1	A1*	D0:1	D1
A0:0	A0*	D0:0	D0

Table 1–3: 80960Cx signal connections for channel probes (cont.)

Section:channel	80960Cx signal	Section:channel	80960Cx signal
C3:7	D/C#	C2:7	BE2#†
C3:6	WAIT#†	C2:6	READY#†
C3:5	W/R#	C2:5	BE3#†
C3:4	PCLK2†	C2:4	BOFF#
C3:3	BE0#†	C2:3§	P_DMA‡
C3:2	DMA#†	C2:2§	BLAST#
C3:1	BE1#†	C2:1§	ADS#†
C3:0	HOLD†	C2:0§	P_BTERM#‡
C1:7	RESET#†	C0:7	SUP#†
C1:6	XINT2#†	C0:6	HOLDA†
C1:5	XINT5#†	C0:5	BTERM†
C1:4	XINT3#†	C0:4	DEN#†
C1:3	NMI#†	C0:3	LOCK#
C1:2	XINT7#†	C0:2	DT/R#†
C1:1	XINT6#†	C0:1	XINT0#†
C1:0	XINT4#†	C0:0	XINT1#†

* Signal grounded on the TMS 161 probe adapter; not an 80960Cx signal.

† Signal not required for disassembly.

‡ Signal synthesized on the TMS 161 probe adapter; not an 80960Cx signal.

§ Clock qualifier channel.

Table 1–4 shows the clock probes and the 80960Cx signal to which they must connect for disassembly to be correct.

Table 1–4: 80960Cx signal connections for clock probes

Section:channel	80960Cx signal
CK:3	WAIT#
CK:2	P_READY#*
CK:1	PCLK1
CK:0	BOFF#

* Signal synthesized on the TMS 161 probe adapter; not an 80960Cx signal.

- Align pin 1 or A1 of your test clip with the corresponding pin 1 or A1 of the 80960Cx microprocessor in your SUT and attach the clip to the microprocessor.



Operating Basics

Setting Up the Support

This section provides information on how to set up the support. Information covers the following topics:

- Channel group definitions
- Clocking options
- Symbol table files

Remember that the information in this section is specific to the operations and functions of the TMS 161 80960Cx support on any Tektronix logic analyzer for which it can be purchased. Information on basic operations describes general tasks and functions.

Before you acquire and disassemble data, you need to load the support and specify setups for clocking and triggering as described in the information on basic operations. The support provides default values for each of these setups, but you can change them as needed.

Channel Group Definitions

The software automatically defines channel groups for the support. The channel groups for the 80960Cx support are Address, Data, Control, DataSize, Intr, and Misc. If you want to know which signal is in which group, refer to the channel assignment tables beginning on page 3–5.

Clocking Options

The TMS 161 support offers a microprocessor-specific clocking mode for the 80960Cx microprocessor. This clocking mode is the default selection whenever you load the 960CA support.

The clocking option for the TMS 161 support is DMA Cycles. The choices are to include or exclude DMA cycles.

A DMA cycle is defined as either the 80960Cx microprocessor on-chip DMA controller performing DMA transfers or as the 80960Cx microprocessor giving up the bus to an alternate device. Back-off cycles, caused when BOFF# is asserted, are also considered to be DMA cycles. All these types of cycles are acquired if you select Included.

A description of how cycles are sampled by the module using the support and probe adapter is found in the *Specifications* chapter.

Disassembly will not be correct with the Internal or External clocking modes. Information on basic operations describes how to use these clock selections for general purpose analysis.

Symbols

The TMS 161 support supplies several symbol table files. The 960CA_Ctrl file replaces specific Control channel group values with symbolic values when Symbolic is the radix for the channel group. Table 2–1 shows the name, bit pattern, and meaning for the symbols in the file 960CA_Ctrl, the Control group symbol table.

Table 2–1: Control group symbol table definitions

Symbol	Control group value				Meaning
	LOCK# D/C#	W/R# P_DMA	BLAST# P_BTERM#	BOFF#	
DMA_READ	X X 0 1		X X 1		A DMA read from memory
DMA_WRITE	X X 1 1		X X 1		A DMA write to memory
DMA	X X X 1		X X 1		Any DMA cycle
FETCH	X 0 0 0		X X 1		An opcode fetch
READ	1 1 0 0		0 X 1		A read from memory
WRITE	1 1 1 0		0 X 1		A write to memory
LOCKED_READ	0 1 0 0		X X 1		The read portion of an atomic memory access
LOCKED_WRITE	0 1 1 0		X X 1		The write portion of an atomic memory access
BURST_READ	1 1 0 0		1 X 1		A burst read from memory
BURST_WRITE	1 1 1 0		1 X 1		A burst write to memory
BURST_TERMINATE	1 1 X 0		X 0 1		The last read or write cycle in a burst mode access
BACK_OFF	X X X X		X X 0		The BOFF# signal is asserted

Table 2–2 shows the name, bit pattern, and meaning for symbols in the file 960CA_Intr, the Intr (Interrupt) group symbol table; this symbol table only supports Dedicated mode, where each signal is seen as an individual interrupt. If your 80960Cx system is configured for Dedicated mode, XINT7 is the second highest-priority interrupt following NMI. The interrupt levels then descend in order to XINT0, which is the lowest-priority interrupt.

If your 80960Cx microprocessor is configured for either Expanded or Mixed interrupt modes, do not use this symbol table. You may copy this table and edit it to support the interrupt mode with which your system is operating. Refer to the information on basic operations for instructions.

Table 2-2: Intr Group symbol table, dedicated mode*

Symbol	Intr group value			Meaning
	NMI# XINT7# XINT6#	XINT5# XINT4# XINT3#	XINT2# XINT1# XINT0#	
NMI	0 X X	X X X	X X X	A nonmaskable interrupt
XINT7	X 0 X	X X X	X X X	External interrupt 7
XINT6	X X 0	X X X	X X X	External interrupt 6
XINT5	X X X	0 X X	X X X	External interrupt 5
XINT4	X X X	X 0 X	X X X	External interrupt 4
XINT3	X X X	X X 0	X X X	External interrupt 3
XINT2	X X X	X X X	0 X X	External interrupt 2
XINT1	X X X	X X X	X 0 X	External interrupt 1
XINT0	X X X	X X X	X X 0	External interrupt 0
-	X X X	X X X	X X X	No pending interrupt

* This symbol table only supports Dedicated mode. Do not use when the 80960Cx microprocessor is operating in Expanded or Mixed mode.

Table 2-3 shows the name, bit pattern, and meaning for the symbols in the 960CA_Misc file, the Misc group symbol table.

Table 2-3: Misc group symbol table definitions

Symbol	Misc group value				Meaning
	RESET# HOLD PCLK2	WAIT# HOLDA DMA#	ADS# SUP# READY#	DT/R# DEN# BTERM#	
SUPERVISOR	X X X	X X X	X 0 X	X X X	The 80960Cx is operating in Supervisor mode
USER	X X X	X X X	X 1 X	X X X	The 80960Cx is operating in User mode

Symbols Used for Symbolic Addressing

The 80960Cx architecture defines a set of system tables that are read by the microprocessor during initialization and software execution. The 80960Cx support supplies data structure symbol tables to provide symbolic address representation for these 80960Cx system data structures.

If you are using only a single data structure symbol table during disassembly, you can directly specify that symbol table in the Channel property page (Channel menu) or in the Disassembly property page (Disassembly Format Definition overlay). You must first use the Symbol Editor to set the base address of the symbol table to the base address of the corresponding system data structure in your system. The Initialization Boot Record symbol table is always located at the same address, so you do not have to set the base.

Only one symbol table can be used with each channel group. This means that if you want to use more than one of these data structure symbol tables, you must merge them together to make one symbol table. Information on basic operations describes how to merge the tables.

You do not have to recreate a new table each time you move the tables in your system as long as the relative difference in address locations does not change. If you move the tables in your system without changing the relative difference in address locations, you only need to redefine the base address for the table.

Table 2–4 shows the name and address range for the symbols in the file 960CA_IBR, the Initialization Boot Record symbol table. This symbol table can only be merged with other symbol tables that have already had the base address added into their values.

Table 2–4: Initialization boot record (IBR) symbol table

Symbol name	Lower address boundary	Upper address boundary
IBR_B_CON	FFFFFF00	FFFFFF03
IBR_FST_I	FFFFFF10	FFFFFF13
IBR_PRCB	FFFFFF14	FFFFFF17
IBR_CHK	FFFFFF18	FFFFFF2F

Table 2–5 shows the name and address range for the symbols in the file 960CA_PRCB, the Process Control Block symbol table.

Table 2–5: Process control block (PRCB) symbol table

Symbol name	Lower address boundary	Upper address boundary
PRCB_FT B	0	3
PRCB_CT B	4	7
PRCB_ACR	8	B
PRCB_FC W	C	F
PRCB_IT B	10	13
PRCB_SP B	14	17
PRCB_IS P	1C	1F
PRCB_IC C	20	23
PRCB_RC C	24	27

Table 2–6 shows the name and address range for the symbols in the file 960CA_SYSP, the System Procedure Table symbol table.

Table 2–6: System procedure table symbol table

Symbol name	Lower address boundary	Upper address boundary
SUP_STK_BASE	30	33
PROC_ENTRY	C0	10F3

Table 2–7 shows the name and address range for the symbols in the file 960CA_IBR, the Interrupt Table symbol table.

Table 2–7: Interrupt Table symbol table

Symbol name	Lower address boundary	Upper address boundary
PENDING_PRI	0	3
PENDING_INT	4	23
INT_VECS	24	403

Table 2–8 shows the name and address range for the symbols in the file 960CA_FAULT, the Fault Table symbol table.

Table 2–8: Fault Table symbol table

Symbol name	Lower address boundary	Upper address boundary
PAR_FAULT	0	7
TR_FAULT	8	F
OP_FAULT	10	17
AR_FAULT	18	1F
CNST_FAULT	28	2F
PRO_FAULT	38	3F
TYPE_FAULT	48	4F

Table 2–9 shows the name and address range for the symbols in the file 960CA_CTBL, the Control Table symbol table.

Table 2-9: Control Table symbol table*

Symbol name	Lower address boundary	Upper address boundary
IPB0	0	3
IPB1	4	7
DAB0	8	B
DAB1	C	F
IMAP0	10	13
IMAP1	14	17
IMAP2	18	1B
ICON	1C	1F
MCON0	20	23
MCON1	24	27
MCON2	28	2B
MCON3	2C	2F
MCON4	30	33
MCON5	34	37
MCON6	38	3B
MCON7	3C	3F
MCON8	40	43
MCON9	44	47
MCON10	48	4B
MCON11	4C	4F
MCON12	50	53
MCON13	54	57
MCON14	58	5B
MCON15	5C	5F
CTBL_RSVD	60	63
BPCON	64	67
TC	68	6B
BCON	6C	6F

* Do not confuse this table with the Control Group symbol table.

Acquiring and Viewing Disassembled Data

This section describes how to acquire data and view it disassembled. Information covers the following topics and tasks:

- Acquiring data
- Viewing disassembled data in various display formats
- Cycle type labels
- How to change the way data is displayed
- How to change disassembled cycles with the mark cycles function

Acquiring Data

Once you load the 80960CA support, choose a clocking mode and specify the trigger, you are ready to acquire and disassemble data.

If you have any problems acquiring data, refer to information on basic operations in your online help or *Appendix A: Error Messages and Disassembly Problems* in the basic operations user manual, whichever is available.

Viewing Disassembled Data

You can view disassembled data in four different display formats: Hardware, Software, Control Flow, and Subroutine. The information on basic operations describes how to select the disassembly display formats.

NOTE. *Selections in the Disassembly property page (the Disassembly Format Definition overlay) must be set correctly for your acquired data to be disassembled correctly. Refer to Changing How Data is Displayed on page 2–11.*

The default display format shows the Address, Data, and Control channel group values for each sample of acquired data.

The disassembler displays special characters and strings in the instruction mnemonics to indicate significant events. Table 2–10 shows these special characters and strings, and gives a definition of what they represent.

Table 2–10: Special characters in the display and meaning

Character or string displayed	Meaning
#	Indicates an immediate value
m	The instruction was manually marked as a program fetch
t	Indicates the number shown is in decimal, such as #12t
****	Indicates there is insufficient data available for complete disassembly of the instruction; the number of asterisks will indicate the width of the data that is unavailable. Each two asterisks represent a byte.
* ILLEGAL INSTRUCTION *	Decoded as an illegal instruction

Hardware Display Format

In Hardware display format, the disassembler displays certain cycle type labels in parentheses. Table 2–11 shows these cycle type labels and gives a definition of the cycle they represent. Reads to interrupt and exception vectors will be labeled with the vector name.

Table 2–11: Cycle type definitions

Cycle type	Definition
(READ)	A basic read cycle
(WRITE)	A basic write cycle
(LOCKED_READ)	The read portion of atomic read/write cycle
(LOCKED_WRITE)	The write portion of atomic read/write cycle
(BURST_READ)	A burst mode read cycle
(BURST_WRITE)	A burst mode write cycle
(DMA_READ)	A processor DMA read cycle (DMA# low or an external processor read cycle (HOLDA# low)
(DMA_WRITE)	A processor DMA write cycle (DMA# low or an external processor write cycle (HOLDA# low)
(FLUSH)*	An instruction fetch that the processor did not use
(REFETCH)*	An instruction that the processor fetched again. Only occurs when the processor cache is turned off
(BACK_OFF)	A back off bus cycle (BOFF# low)
(EXTENSION)*	The second word of the two-word instruction
(PREFETCH_BYTE)*	The 2nd, 3rd and 4th byte of an instruction in an 8-bit memory region
(PREFETCH_HALF-WORD)*	The 2nd 16-bit word of an instruction in a 16-bit memory region
(FLUSH: PREDICTION FAIL)*	The flushing occurring due to CONDITIONAL branches not being taken with prediction flag set to TRUE

* Computed cycle type.

Figure 2–1 shows an example of the Hardware display.

1	2	3	4	5
Sample	Address	Data	Mnemonics	Timestamp
15	8000001E	----8058	(PREFETCH HALF-WORD)	540 ns
16	80000020	----0004	(EXTENSION)	450 ns
17	80000022	----0000	(PREFETCH HALF-WORD)	450 ns
18	80000024	----3000	LDOS 00004500, G6	450 ns
19	80000026	----88B0	(PREFETCH HALF-WORD)	450 ns
20	80000028	----4500	(EXTENSION)	450 ns
21	8000002A	----0000	(PREFETCH HALF-WORD)	460 ns
22	8000002C	----1400	LDOS 8000004C, R8	440 ns
23	8000002E	----8840	(PREFETCH HALF-WORD)	550 ns
24	800004E8	----0000	(BURST_READ)	530 ns
25	800004EC	----0000	(BURST_READ)	790 ns
26	800004EC	----0000	(BURST_READ)	20 ns
27	800004EC	----0000	(BURST_READ)	30 ns
28	00004500	00000000	(READ)	30 ns
29	00004500	00000000	(READ)	1.090 us
30	80000030	----0018	(EXTENSION)	1.520 us
31	80000032	----0000	(PREFETCH HALF-WORD)	450 ns
32	80000034	----0100	LDA 100, R4	450 ns
33	80000036	----8C20	(PREFETCH HALF-WORD)	450 ns
34	80000038	----0484	SYSCTL R4, R8, R8	450 ns
35	8000003A	----6542	(PREFETCH HALF-WORD)	450 ns
36	8000003C	----3000	LDIB 00004500, G6	450 ns

Figure 2–1: Hardware display format

- 1 **Sample Column.** Lists the memory locations for the acquired data.
- 2 **Address Group.** Lists data from channels connected to the 80960Cx Address bus.
- 3 **Data Group.** Lists data from channels connected to the 80960Cx Data bus.
- 4 **Mnemonic Column.** Lists the disassembled instructions and cycle types.
- 5 **Control Group.** Lists data from channels connected to 80960Cx microprocessor control signals (shown symbolically).
- 6 **Timestamp.** Lists the timestamp values when a timestamp selection is made. Information on basic operations describes how you can select a timestamp.

Software Display Format

The Software display format shows only the first fetch of executed instructions. Flushed cycles and extensions are not shown, even though they are part of the executed instruction. The display is designed to resemble assembly language listings.

Control Flow Display Format

The Control Flow display format shows only the first fetch of instructions that change the flow of control. Instructions that do not actually change the control flow are not displayed. An example of this is a conditional branch that is not taken.

Interrupts will not be displayed in the Control Flow format. The 80960Cx microprocessor does not have an instruction that indicates when an interrupt is being serviced. If you trigger on the start of an interrupt service routine, the interrupt only displays in the Hardware and Software display formats.

Instructions that generate a change in the flow of control in an 80960Cx microprocessor are as follows:

CALL	B	BX
CALLS	BAL	FMARK
CALLX	BALX	RET

Instructions that might generate a change in the flow of control based on a condition or setting in the control register in an 80960Cx microprocessor are as follows:

BBC	CMPIBGE	FAULTE
BBS	CMPIBL	FAULTG
BE	CMPIBLE	FAULTGE
BG	CMPIBNE	FAULTL
BGE	CMPIBNO	FAULTLE
BL	CMPIBO	FAULTNE
BLE	CMPOBE	FAULTNO
BNE	CMPOBG	FAULTO
BNO	CMPOBGE	MARK
BO	CMPOBL	SYSCTL
CMPIBE	CMPOBLE	
CMPIBG	CMPOBNE	

When the disassembler encounters a Call, Branch, or Return instruction for which the destination address cannot be calculated, such as call indirect through a register, the disassembler assumes the data at the address break was an executed instruction. You can use the mark opcode function to correct the display.

Some extremely long instructions, such as LD 10000000 (R10) [R12*16], R12 might be truncated. In this example, the R12 might be missing on the display.

Conditional branch instructions that have a prediction extension of .t and do not cause a break in instruction flow can cause invalid disassembly. You can use the mark opcode function to correct the display.

Subroutine Display Format

The Subroutine format displays subroutine calls and returns only. The displayed subroutine calls and returns include interrupts and returns from interrupts.

Interrupts do not display in the Subroutine format. The 80960Cx does not have an instruction that indicates when an interrupt is being serviced. If you trigger on the start of an interrupt service routine, the interrupt only displays in the Hardware and Software display formats.

Instructions that generate a subroutine call or return in an 80960Cx microprocessor are as follows:

CALL	CALLX	BALX
CALLS	BAL	RET

Changing How Data is Displayed

There are fields and features that allow you to further modify displayed data to suit your needs. You can make selections unique to the 80960Cx support to do the following tasks:

- Change how data is displayed across all display formats
- Change the interpretation of disassembled cycles

Optional Display Selections

You can make optional display selections for disassembled data to help you analyze the data. You can make these selections in the Disassembly property page for the 102/136-channel module, or in the Disassembly Format Definition overlay for the 96-channel module.

In addition to the common display options (described in the information on basic operations), you can change the displayed data in the following ways:

- Specify three memory regions that the 80960Cx microprocessor accesses in 8-bit mode.
- Specify three memory regions that the 80960Cx microprocessor accesses in 16-bit mode.

The 80960Cx support has six additional fields for memory region assignments. The following fields appear in the area indicated in the information on basic operations:

- 8-Bit Memory Region 1
- 8-Bit Memory Region 2
- 8-Bit Memory Region 3
- 16-Bit Memory Region 1

- 16-Bit Memory Region 2
- 16-Bit Memory Region 3

You can specify each of up to three memory regions as 8- or 16-bit mode for the disassembler to identify when the 80960Cx microprocessor accesses it. To indicate that accesses to that memory region are displayed as 8- or 16-bit mode, select a hexadecimal value for the memory region (0 to F). The default values are F for 8-Bit Memory Region 1 and None for the rest of the memory regions. The value None indicates that the memory region is defined as 32-bit mode.

Burst or Burst Pipelining Mode Addressing

The disassembler will only latch the initial address and BE3#–BE0# bus values during Burst or Burst Pipelining modes. These initial values are repeatedly displayed (up to three additional times) as the address and BE3#–BE0# values for any and all cycles that occur during the burst.

When defining a trigger program, you can use data from any cycle with the initial address and BE3#–BE0# value in a memory region where Burst is enabled as the trigger event. Other address and BE3#–BE0# values should not be used as they will never be found.

A0 and A1 Signals

The A0 and A1 address signals do not exist on the 80960Cx microprocessor. Both these signal channels are grounded on the probe adapter; they will always have a value of 0. Consequently, addresses are always an integral multiple of four. This means that you can only trigger on a hexadecimal address that ends with a 0, 4, 8, or C. When triggering on a burst, the address value will always end in 0.

Table 2–12 shows requirements for triggering on specific addresses.

Table 2–12: Triggering on specific addresses

Desired address	Set trigger values to
XXXXXXXX0	XXXXXXXX0
XXXXXXXX4	XXXXXXXX0
XXXXXXXX8	XXXXXXXX0 or XXXXXXX8
XXXXXXXXC	XXXXXXXX0 or XXXXXXX8

Marking Cycles

The disassembler has a Mark Opcode function that allows you to change the interpretation of a cycle type. Using this function, you can select a cycle and change it to one of the following cycle types:

- Opcode (the first word of an instruction)
- Extension (a subsequent word of an instruction)
- Flush (an opcode or extension that is fetched but not executed)

Mark selections are as follows:

```
OPCODE
Extension
Flush
Undo Mark
```

Information on basic operations contains more details on marking cycles.

Viewing an Example of Disassembled Data

A demonstration system file is provided so you can see an example of how your 80960Cx microprocessor bus cycles and instruction mnemonics look when they are disassembled. Viewing the system file is not a requirement for preparing the module for use. You can view the system file without connecting the logic analyzer to your SUT.



Specifications

Specifications

This chapter contains the following information:

- Probe adapter description
- Specification tables
- Dimensions of the probe adapter
- Channel assignment tables
- Description of how the module acquires 80960Cx signals
- List of other accessible microprocessor signals and extra acquisition channels

Probe Adapter Description

The probe adapter is nonintrusive hardware that allows the logic analyzer to acquire data from a microprocessor in its own operating environment with little effect, if any, on that system. Information on basic operations contains a figure showing the logic analyzer connected to a typical probe adapter. Refer to that figure while reading the following description.

The probe adapter consists of a circuit board and a socket for a 80960Cx microprocessor. The probe adapter connects to the microprocessor in the SUT. Signals from the microprocessor-based system flow from the probe adapter to the channel groups and through the probe signal leads to the module.

All circuitry on the probe adapter is powered from the SUT.

The probe adapter accommodates the Intel 80960Cx microprocessor in a 168-pin PGA package.

Configuring the Probe Adapter

You can set up each memory region in the 80960Cx system through software. The probe adapter DIP switches must be set up to match your system's memory region setup. To configure the probe adapter, follow these steps:

1. Determine how the 80960Cx system is configured in each of its regions. Compare the lower three bits for each region to the bit values in Table 1–1 to determine how to set the DIP switch on the probe adapter.
2. Use Table 1–2 to determine which DIP switch to set for each memory region.

Specifications

These specifications are for a probe adapter connected between a compatible Tektronix logic analyzer and a SUT. Table 3–1 shows the electrical requirements the SUT must produce for the support to acquire correct data.

In Table 3–1, for the 102/136-channel module, one podlet load is 20 k Ω in parallel with 2 pF. For the 96-channel module, one podlet load is 100 k Ω in parallel with 10 pF.

Table 3–1: Electrical specifications

Characteristics	Requirements	
SUT DC power requirements		
Voltage	4.5 to 5.5 VDC	
Current	< 350 mA max	
SUT clock		
Clock rate	33 MHz max*	
Clock pulse width		
Low time	4 ns min	
High time	4 ns min	
Minimum setup time required†		
A31:28, READY#	10 ns	
DMA#, HOLDA, BTERM#	11.5 ns	
ADS#, BLAST#	6.5 ns	
All other signals	5 ns	
Minimum hold time required†		
All signals	0 ns	
Measured typical SUT signal loading	AC load ‡	DC load §
A31-A28	< 30 pF	100 k Ω in parallel with 1 CE22V10 load
A27-A2	< 25 pF	100 k Ω
D31-D0	< 25 pF	100 k Ω
PCLK1	< 20 pF	100 k Ω
PCLK2	< 25 pF	100 k Ω in parallel with 1 CE22V10 load
WAIT#	< 30 pF	50 k Ω

Table 3–1: Electrical specifications (cont.)

Characteristics	Requirements	
READY#, BTERM#, DMA#, HOLDA	< 30 pF	100 k Ω in parallel with 1 16L8 load
BOFF#¶	< 30 pF	10 k Ω in parallel with 50 k Ω
ADS#, BE3#-BE0#, BLAST#, W/R#, P_DMA, D/C#, HOLD, DACK3#-DACK0#, LOCK#, NMI#, RESET#, SUP#, XINT7#-XINIT0#	< 25 pF	100 k Ω

- * Specification at time of printing. Contact your logic analyzer sales representative for current information on the fastest devices supported.
- † Setup and hold times are with respect to the PCLK1 signal from the probe adapter.
- ‡ This includes run capacitance and input capacitance of any ICs (excluding the 80960Cx) on the probe adapter board and the input capacitance of the probes.
- § This includes DC impedance of any parts (excluding the 80960Cx microprocessor) on the probe adapter board and the DC impedance of the probes.
- ¶ The pin that connects to BOFF# was not connected to any signal in early versions of the 80960Cx microprocessor. The probe adapter has a 10 k Ω pullup resistor to remain compatible with both versions of the 80960Cx microprocessor.

Table 3–2 shows the environmental specifications.

Table 3–2: Environmental specifications†

Characteristic	Description
Temperature	
Maximum operating	+50° C (+122° F)*
Minimum operating	° C (+32° F)
Nonoperating	–625° C to +855° C (–785° F to +1855° F)
Humidity	0 to 95% relative humidity (noncondensing)
Altitude	
Operating	4.5 km (15,000 ft) maximum
Nonoperating	15 km (50,000 ft) maximum
Electrostatic immunity	The probe adapter is static sensitive

* **Not to exceed 80960Cx microprocessor thermal considerations. Forced air cooling may be required across the CPU.**

† **Designed to meet Tektronix standard 062-2847-00 class 5.**

Table 3–3 shows the certifications and compliances that apply to the probe adapter.

Table 3–3: Certifications and compliances

EC Compliance	There are no current European Directives that apply to this product.
---------------	--

Figure 3–1 shows the dimensions of the probe adapter. Information on basic operations shows the vertical clearance of the channel and clock probes when connected to a probe adapter in the description of general requirements and restrictions.

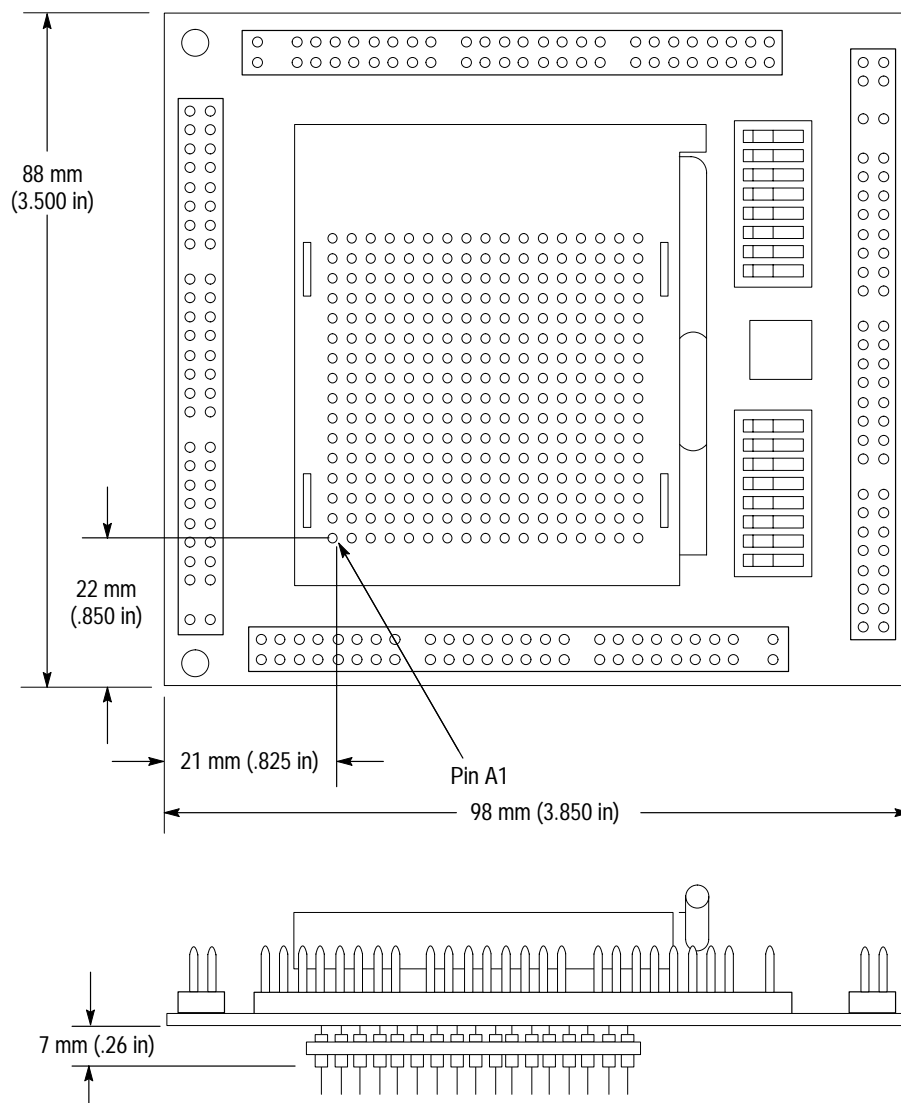


Figure 3–1: Minimum clearance of the standard probe adapter

Channel Assignments

Channel assignments shown in Table 3–4 through Table 3–10 use the following conventions:

- All signals are required by the support unless indicated otherwise.

- Channels are shown starting with the most significant bit (MSB) descending to the least significant bit (LSB).
- Channel group assignments are for all modules unless otherwise noted.
- A pound sign (#) following a signal name indicates an active low signal

Table 3–4 shows the probe section and channel assignments for the Address group and the microprocessor signal to which each channel connects. By default, this channel group is displayed in hexadecimal.

Table 3–4: Address group channel assignments

Bit order	Section: channel	80960Cx signal name
31	A3:7	A31
30	A3:6	A30
29	A3:5	A29
28	A3:4	A28
27	A3:3	A27
26	A3:2	A26
25	A3:1	A25
24	A3:0	A24
23	A2:7	A23
22	A2:6	A22
21	A2:5	A21
20	A2:4	A20
19	A2:3	A19
18	A2:2	A18
17	A2:1	A17
16	A2:0	A16
15	A1:7	A15
14	A1:6	A14
13	A1:5	A13
12	A1:4	A12
11	A1:3	A11
10	A1:2	A10
9	A1:1	A9
8	A1:0	A8
7	A0:7	A7
6	A0:6	A6
5	A0:5	A5

Table 3–4: Address group channel assignments

Bit order	Section: channel	80960Cx signal name
4	A0:4	A4
3	A0:3	A3
2	A0:2	A2
1	A0:1	A1*
0	A0:0	A0*

* Signal grounded on the TMS 161 probe adapter; not an 80960Cx signal.

Table 3–5 shows the probe section and channel assignments for the Data group and the microprocessor signal to which each channel connects. By default, this channel group is displayed in hexadecimal.

Table 3–5: Data group channel assignments

Bit order	Section: channel	80960Cx signal name
31	D3:7	D31
30	D3:6	D30
29	D3:5	D29
28	D3:4	D28
27	D3:3	D27
26	D3:2	D26
25	D3:1	D25
24	D3:0	D24
23	D2:7	D23
22	D2:6	D22
21	D2:5	D21
20	D2:4	D20
19	D2:3	D19
18	D2:2	D18
17	D2:1	D17
16	D2:0	D16
15	D1:7	D15
14	D1:6	D14
13	D1:5	D13
12	D1:4	D12

Table 3–5: Data group channel assignments

Bit order	Section: channel	80960Cx signal name
11	D1:3	D11
10	D1:2	D10
9	D1:1	D9
8	D1:0	D8
7	D0:7	D7
6	D0:6	D6
5	D0:5	D5
4	D0:4	D4
3	D0:3	D3
2	D0:2	D2
1	D0:1	D1
0	D0:0	D0

Table 3–6 shows the probe section and channel assignments for the Control group and the microprocessor signal to which each channel connects. By default, this channel group is displayed symbolically.

Table 3–6: Control group channel assignments

Bit order	Section: channel	80960Cx signal name
6	C0:3	LOCK#
5	C3:7	D/C#
4	C3:5	W/R#
3	C2:3†	P_DMA*
2	C2:2†	BLAST#
1	C2:0†	P_BTERM#*
0	C2:4	BOFF#

* Signal synthesized on the TMS 161 probe adapter; not an 80960Cx signal.

† Clock qualifier channel.

Table 3–7 shows the probe section and channel assignments for the DataSize group and the microprocessor signal to which each channel connects. By default, this channel group is displayed in binary.

Table 3–7: DataSize group channel assignments

Bit order	Section: channel	80960Cx signal name
3	C2:5	BE3#*
2	C2:7	BE2#*
1	C3:1	BE1#*
0	C3:3	BE0#*

* Signals not required for disassembly.

Table 3–8 shows the probe section and channel assignments for the Intr group and the microprocessor signal to which each channel connects. By default, this channel group is not visible.

Table 3–8: Intr group channel assignments

Bit order	Section: channel	80960Cx signal name
8	C1:3	NMI#*
7	C1:2	XINT7#*
6	C1:1	XINT6#*
5	C1:5	XINT5#*
4	C1:0	XINT4#*
3	C1:4	XINT3#*
2	C1:6	XINT2#*
1	C0:0	XINT1#*
0	C0:1	XINT0#*

* Signal not required for disassembly.

Table 3–9 shows the probe section and channel assignments for the Misc group and the microprocessor signal to which each channel connects. By default, this channel group is not visible.

Table 3–9: Misc group channel assignments

Bit order	Section: channel	80960Cx signal name
11	C1:7	RESET#*
10	C3:0	HOLD*
9	C3:4	PCLK2*
8	C3:6	WAIT#*
7	C0:6	HOLDA*
6	C3:2	DMA#*
5	C2:1†	ADS#*
4	C0:7	SUP#*
3	C2:6	READY#*
2	C0:2	DT/R#*
1	C0:4	DEN#*
0	C0:5	BTERM*

* Signal not required for disassembly.

† Clock qualifier channel.

Table 3–10 shows the probe section and channel assignments for the clock probes (not part of any group) and the 80960Cx signal to which each channel connects.

Table 3–10: Clock channel assignments

Channel	80960Cx signal name
CLK:3	WAIT#
CLK:2	P_READY#*
CLK:1	PCLK1
CLK:0	BOFF#

* Signal synthesized on the TMS 161 probe adapter, not on an 80960Cx signal.

These channels are used only to clock in data; they are not acquired or displayed. To acquire data from any of the signals shown in Table 3–10, you must connect another channel probe to the signal, a technique called double probing.

How Data is Acquired

This part of this chapter explains how the module acquires 80960Cx signals using the TMS 161 software and probe adapter. This part also provides additional information on microprocessor signals accessible on or not accessible on the probe adapter, and on extra acquisition channels available for you to use for additional connections.

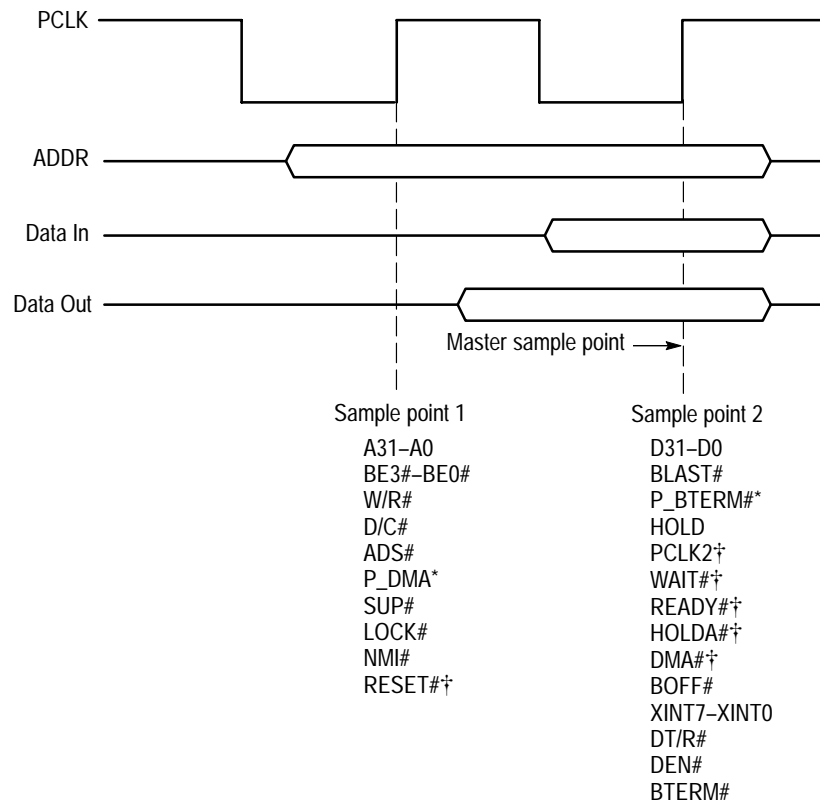
Custom Clocking

A special clocking program is loaded to the module every time you load the 960CA support. This special clocking is called Custom.

With Custom clocking, the module logs in signals from multiple groups of channels at different times as they become valid on the 80960Cx bus. The module then sends all the logged-in signals to the trigger machine and to the acquisition memory of the module for storage.

In Custom clocking, the module clocking state machine (CSM) generates one master sample for each microprocessor bus cycle, no matter how many clock cycles are contained in the bus cycle.

Figure 3–2 shows the sample points and the master sample point.



* Signals generated on the probe adapter board.

† Signals only useful for asynchronous timing (Internal). They are not valid when clocked synchronous (Custom or External).

Figure 3-2: 80960Cx bus timing

In pipeline and burst cycles with zero wait states, these sample points occur at the same time. The Custom clocking algorithm does not log in data during software wait states. The clocking algorithm also does not log in data during hardware wait states, caused by the READY# input, if the DIP switches on the probe adapter are set correctly. If the DIP switches are set incorrectly, invalid data may be acquired even in regions where READY# is not used. Refer to the discussion on *Configuring the Probe Adapter* on page 1-3 for information on how to set the DIP switches.

After the acquisition is complete, the disassembler reads the acquisition memory. Since each memory location contains 80960Cx data for a complete bus cycle, the disassembler is able to deduce the kind of bus activity that took place. For example, if an opcode fetch occurred, the disassembler converts the data bus into the opcode the data bus represents.

Clocking Options

The clocking algorithm for the 80960Cx support has two variations: Alternate Bus Master Cycles Excluded and Alternate Bus Master Cycles Included.

DMA Cycles Included. When the on-chip DMA controller is functioning, the DMA# signal is active and bus cycles look just like normal bus cycles. The P_DMA signal is always stored as a high during these cycles indicating to the disassembler that a DMA cycle occurred.

If HOLDA is active, then the 80960Cx microprocessor has given up the bus to another device. The design of the 80960Cx hardware affects what data will be logged in. The logic analyzer only samples signals at the 80960Cx pins. To properly log in bus activity, any buffers between the 80960Cx and the alternate bus driver must be enabled and pointed towards the 80960Cx. The possible 80960Cx hardware and clocking interactions are as follows:

- If the alternate device drives the same control lines as the 80960Cx and the 80960Cx sees these signals, alternate bus activity is logged in just like normal bus cycles except that P_DMA will be asserted.
- If none of the control lines are driven or if the 80960Cx cannot see them, the logic analyzer still logs in a DMA cycle. The information present on the bus one clock period prior to the deassertion of HOLDA is logged in as the DMA bus cycle.
- If some of the 80960Cx control signals are visible, but not all of them, the logic analyzer logs in what it determines is valid from the visible control signals. It also logs in the information previously present on the remaining bus signals one clock period prior to the deassertion of HOLDA. In all cases, P_DMA is logged in as high.

When the DMA selection is set to Included, back-off cycles are logged in as well. When BOFF# is asserted, a back-off state has been requested and the 80960Cx will give up the bus on the next clock. The logic analyzer aborts the bus cycle that it is currently logging in. The 80960Cx restarts this cycle when BOFF# is deasserted. A back-off cycle will be logged in using one of the three interactions listed above for HOLDA except that BOFF# is stored low in each case.

DMA Cycles Excluded. Whenever the logic analyzer is about to log in the first sample of a bus cycle and it detects that P_DMA is high, no data is logged in. No DMA cycles caused by either DMA# or HOLDA are logged in with this selection. Backoff cycles caused by BOFF# are not logged in.

Synthesized Signals

The probe adapter must synthesize five signals in order to acquire valid data. Table 3–11 describes them. Refer to the previous discussions on including and excluding DMA cycles for a description of how these signals are used.

Table 3–11: Synthesized signals

Signal	Description
P_DMA	Indicates that a DMA cycle or another device controls the bus. DMA# is combined with HOLDA to create this signal. This signal is asserted (high) when either DMA# or HOLDA is asserted.
P_BTERM#	Derived from the DIP switches on the probe adapter. If the switch is open, P_BTERM# is the same as BTERM#. If the switch is closed, P_BTERM# is deasserted (high).
P_READY#	Derived from the DIP switches on the probe adapter. If the switch is open, P_READY# is the same as READY#. If the switch is closed, P_READY# is asserted (low).
A1	Grounded on the probe adapter
A0	Grounded on the probe adapter

Alternate Microprocessor Connections

You can connect to microprocessor signals that are not required by the support so that you can do more advanced timing analysis. For a list of signals required or not required for disassembly, refer to the channel assignment tables beginning on page 3–5.

Signals On the Probe Adapter

All 80960Cx microprocessor signals are accessible on the probe adapter.

Extra Channels

Table 3–12 lists extra sections and channels that are left after you have connected all the probes used by the support. You can use these extra channels to make alternate SUT connections.

Table 3–12: Extra module sections and channels

Module	Section: channels
102-channels	Qual:1, Qual:0
136-channels	E3:7-0, E2:7-0, E1:7-0, E0:7-0, Qual:3-0
96-channels	None

These channels are not defined in any channel group and data acquired from them is not displayed. To display data, you will need to define a channel group.

WARNING

The following servicing instructions are for use only by qualified personnel. To avoid injury, do not perform any servicing other than that stated in the operating instructions unless you are qualified to do so. Refer to all Safety Summaries before performing any service.



Maintenance

Maintenance

This section contains a circuit description of the probe adapter.

Probe Adapter Circuit Description

Most signals are routed directly to square pins where they connect to the channel probe inputs. There are three exceptions: the P_DMA, P_READY#, and P_BTERM# signals. All three of these signals are driven by a 16L8 PAL.

The DMA# and HOLDA 80960Cx outputs are combined to create P_DMA. P_DMA is high anytime either DMA# or HOLDA is active.

A 22V10 PAL, 16 DIP switches, the upper four address lines A31–A28, and PCLK2 are used to generate a signal named P_RDY_EN. The 80960Cx microprocessor uses its upper four address lines to map its memory into 16 regions. Each region is software programmable.

The READY# and BTERM# signal inputs may be masked out in each of the regions. You must open the DIP switch(s) that corresponds to region(s) where the READY# and BTERM# signals are enabled. This will cause the P_RDY_EN signal to be high whenever the address is in a region where READY# and BTERM# are active.

The P_RDY_EN signal is combined with the READY# and BTERM# signals to create the P_READY# and P_BTERM# signals. In a memory region where the READY# signal is enabled, P_READY# will be the same as READY#. In memory regions where the READY# signal is not enabled, P_READY# will be low regardless of the value of READY#.

In memory regions where the BTERM# signal is enabled, P_BTERM# will be the same as BTERM#. In memory regions where the BTERM# signal is not enabled, P_BTERM# will be high regardless of the value of BTERM#.

The 22V10 PAL is programmed for 21 inputs and one output. The PAL is programmed to decode the four address lines into 16 outputs. Each output is 'ANDed' with a DIP switch, and then all of the AND gate outputs are 'ORed' together. The OR output is clocked into a flip flop whose output becomes P_RDY_EN. When the DIP switch is open, the input to the AND gate is high. When the DIP switch is closed, the input to the AND gate is low.

The probe adapter does not have a special mode to support timing analysis. Instead the clocks are double probed (where applicable) and other signals not required for disassembly are connected to the remaining probe channels.

The BOFF# signal is not present on early versions of the 80960Cx microprocessor. This signal is used as a clock qualifier by the TMS 161. On early 80960Cx microprocessors, this pin was not connected. A 10 k Ω resistor has been added between BOFF# and Vcc.

On versions of the 80960Cx that do not have BOFF#, the resistor will pull this pin high so that the clock qualifier will be in the inactive state. On versions of the 80960Cx that have BOFF#, the 10 k Ω pull up resistor is easily driven adding very little load.

Replacing Signal Leads

Information on basic operations describes how to replace signal leads (individual channel and clock probes).

Replacing Protective Sockets

Information on basic operations describes how to replace protective sockets.



Replaceable Electrical Parts

Replaceable Electrical Parts

This chapter contains a list of the replaceable electrical components for the TMS 161 80960Cx microprocessor support. Use this list to identify and order replacement parts.

Parts Ordering Information

Replacement parts are available through your local Tektronix field office or representative.

Changes to Tektronix products are sometimes made to accommodate improved components as they become available and to give you the benefit of the latest improvements. Therefore, when ordering parts, it is important to include the following information in your order:

- Part number
- Instrument type or model number
- Instrument serial number
- Instrument modification number, if applicable

If you order a part that has been replaced with a different or improved part, your local Tektronix field office or representative will contact you concerning any change in part number.

Change information, if any, is located at the rear of this manual.

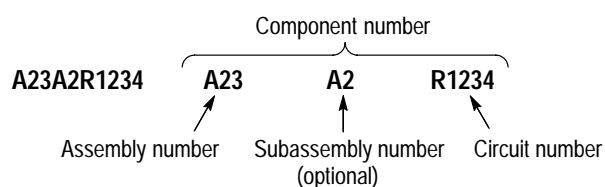
Using the Replaceable Electrical Parts List

The tabular information in the Replaceable Electrical Parts List is arranged for quick retrieval. Understanding the structure and features of the list will help you find all of the information you need for ordering replacement parts. The following table describes each column of the electrical parts list.

Parts list column descriptions

Column	Column name	Description
1	Component number	<p>The component number appears on diagrams and circuit board illustrations, located in the diagrams section. Assembly numbers are clearly marked on each diagram and circuit board illustration in the <i>Diagrams</i> section, and on the mechanical exploded views in the <i>Replaceable Mechanical Parts</i> list section. The component number is obtained by adding the assembly number prefix to the circuit number (see Component Number illustration following this table).</p> <p>The electrical parts list is arranged by assemblies in numerical sequence (A1, with its subassemblies and parts, precedes A2, with its subassemblies and parts).</p> <p>Chassis-mounted parts have no assembly number prefix, and they are located at the end of the electrical parts list.</p>
2	Tektronix part number	Use this part number when ordering replacement parts from Tektronix.
3 and 4	Serial number	Column three indicates the serial number at which the part was first effective. Column four indicates the serial number at which the part was discontinued. No entry indicates the part is good for all serial numbers.
5	Name & description	An item name is separated from the description by a colon (:). Because of space limitations, an item name may sometimes appear as incomplete. Use the U.S. Federal Catalog handbook H6-1 for further item name identification.
6	Mfr. code	This indicates the code number of the actual manufacturer of the part.
7	Mfr. part number	This indicates the actual manufacturer's or vendor's part number.

Abbreviations Abbreviations conform to American National Standard ANSI Y1.1–1972.

Component Number


Read: Resistor 1234 (of Subassembly 2) of Assembly 23

List of Assemblies A list of assemblies is located at the beginning of the electrical parts list. The assemblies are listed in numerical order. When a part's complete component number is known, this list will identify the assembly in which the part is located.

Chassis Parts Chassis-mounted parts and cable assemblies are located at the end of the Replaceable Electrical Parts List.

Mfr. Code to Manufacturer Cross Index The table titled Manufacturers Cross Index shows codes, names, and addresses of manufacturers or vendors of components listed in the parts list.

Manufacturers cross index

Mfr. code	Manufacturer	Address	City, state, zip code
TK2058	TDK CORPORATION OF AMERICA	1600 FEEHANVILLE DRIVE	MOUNT PROSPECT, IL 60056
50139	ALLEN-BRADLEY CO ELECTRONIC COMPONENTS	1414 ALLEN BRADLEY DR	EL PASO TX 79936
53387	3M COMPANY ELECTRONIC PRODUCTS DIV	3M AUSTIN CENTER	AUSTIN TX 78769-2963
57924	BOURNS INC INTEGRATED TECHNOLOGY DIVISION	1400 NORTH 1000 WEST	LOGAN UT 84321
80009	TEKTRONIX INC	14150 SW KARL BRAUN DR PO BOX 500	BEAVERTON OR 97077-0001
81073	GRAYHILL INC	561 HILLGROVE AVE PO BOX 10373	LA GRANGE IL 60525-5914

Replaceable electrical parts list

Component number	Tektronix part number	Serial no. effective	Serial no. discont'd	Name & description	Mfr. code	Mfr. part number
A1	671-1973-00			CIRCUIT BD ASSY:TMS 161 80960CA TARGET HEAD	80009	671197300
A1C114	283-5004-00			CAP,FXD,CERAMIC:MLC;0.1UF,10%,25V,X7R,1206	TK2058	C3216X7R1E104K-
A1C115	283-5004-00			CAP,FXD,CERAMIC:MLC;0.1UF,10%,25V,X7R,1206	TK2058	C3216X7R1E104K-
A1C116	283-5004-00			CAP,FXD,CERAMIC:MLC;0.1UF,10%,25V,X7R,1206	TK2058	C3216X7R1E104K-
A1C211	283-5004-00			CAP,FXD,CERAMIC:MLC;0.1UF,10%,25V,X7R,1206	TK2058	C3216X7R1E104K-
A1C220	283-5004-00			CAP,FXD,CERAMIC:MLC;0.1UF,10%,25V,X7R,1206	TK2058	C3216X7R1E104K-
A1J100	131-5267-00			CONN,HDR:PCB,;MALE,STR,2 X 40,0.1 CTR,0.235 (STANDARD ONLY)	53387	2480-6122-TB
A1J100	131-5268-00			CONN,HDR:PCB,;MALE,RTANG,2 X 40,0.1CTR,0.235 MLG X 0.110 TAIL,30 GOLD	53387	2480-5122-TB
A1J101	131-5267-00			CONN,HDR:PCB,;MALE,STR,2 X 40,0.1 CTR,0.235 (STANDARD ONLY)	53387	2480-6122-TB
A1J101	131-5268-00			CONN,HDR:PCB,;MALE,RTANG,2 X 40,0.1CTR,0.235 MLG X 0.110 TAIL,30 GOLD	53387	2480-5122-TB
A1J110	131-5267-00			CONN,HDR:PCB,;MALE,STR,2 X 40,0.1 CTR,0.235 (STANDARD ONLY)	53387	2480-6122-TB
A1J110	131-5268-00			CONN,HDR:PCB,;MALE,RTANG,2 X 40,0.1CTR,0.235 MLG X 0.110 TAIL,30 GOLD	53387	2480-5122-TB
A1J120	131-5267-00			CONN,HDR:PCB,;MALE,STR,2 X 40,0.1 CTR,0.235 (STANDARD ONLY)	53387	2480-6122-TB
A1J120	131-5268-00			CONN,HDR:PCB,;MALE,RTANG,2 X 40,0.1CTR,0.235 MLG X 0.110 TAIL,30 GOLD	53387	2480-5122-TB
A1J121	131-5267-00			CONN,HDR:PCB,;MALE,STR,2 X 40,0.1 CTR,0.235 (STANDARD ONLY)	53387	2480-6122-TB
A1J121	131-5268-00			CONN,HDR:PCB,;MALE,RTANG,2 X 40,0.1CTR,0.235 MLG X 0.110 TAIL,30 GOLD	53387	2480-5122-TB
A1J122	131-5267-00			CONN,HDR:PCB,;MALE,STR,2 X 40,0.1 CTR,0.235 (STANDARD ONLY)	53387	2480-6122-TB
A1J122	131-5268-00			CONN,HDR:PCB,;MALE,RTANG,2 X 40,0.1CTR,0.235 MLG X 0.110 TAIL,30 GOLD	53387	2480-5122-TB
A1J200	131-5267-00			CONN,HDR:PCB,;MALE,STR,2 X 40,0.1 CTR,0.235 (STANDARD ONLY)	53387	2480-6122-TB
A1J200	131-5268-00			CONN,HDR:PCB,;MALE,RTANG,2 X 40,0.1CTR,0.235 MLG X 0.110 TAIL,30 GOLD	53387	2480-5122-TB
A1J201	131-5267-00			CONN,HDR:PCB,;MALE,STR,2 X 40,0.1 CTR,0.235 (STANDARD ONLY)	53387	2480-6122-TB
A1J202	131-5267-00			CONN,HDR:PCB,;MALE,STR,2 X 40,0.1 CTR,0.235 (STANDARD ONLY)	53387	2480-6122-TB
A1J202	131-5268-00			CONN,HDR:PCB,;MALE,RTANG,2 X 40,0.1CTR,0.235 MLG X 0.110 TAIL,30 GOLD	53387	2480-5122-TB
A1J210	131-5267-00			CONN,HDR:PCB,;MALE,STR,2 X 40,0.1 CTR,0.235 (STANDARD ONLY)	53387	2480-6122-TB
A1J210	131-5268-00			CONN,HDR:PCB,;MALE,RTANG,2 X 40,0.1CTR,0.235 MLG X 0.110 TAIL,30 GOLD	53387	2480-5122-TB
A1J220	131-5267-00			CONN,HDR:PCB,;MALE,STR,2 X 40,0.1 CTR,0.235 (STANDARD ONLY)	53387	2480-6122-TB

Replaceable electrical parts list (cont.)

Component number	Tektronix part number	Serial no. effective	Serial no. discont'd	Name & description	Mfr. code	Mfr. part number
A1J220	131-5268-00			CONN,HDR:PCB,;MALE,RTANG,2 X 40,0.1CTR,0.235 MLG X 0.110 TAIL,30 GOLD	53387	2480-5122-TB
A1J221	131-5267-00			CONN,HDR:PCB,;MALE,STR,2 X 40,0.1 CTR,0.235 (STANDARD ONLY)	53387	2480-6122-TB
A1J221	131-5268-00			CONN,HDR:PCB,;MALE,RTANG,2 X 40,0.1CTR,0.235 MLG X 0.110 TAIL,30 GOLD	53387	2480-5122-TB
A1J222				(STANDARD ONLY)		
A1J222	131-5268-00			CONN,HDR:PCB,;MALE,RTANG,2 X 40,0.1CTR,0.235 MLG X 0.110 TAIL,30 GOLD	53387	2480-5122-TB
A1R109	321-5030-00			RES,FXD:THICK FILM;10.0K OHM,1%,0.125W,TC=100 PPM	50139	BCK1002FT
A1R210	307-5041-00			RES NTWK,FXD,FI:4.7K OHM,2%,0.125W	57924	4816P-T02-472
A1R220	321-5026-00			RES,FXD:THICK FILM;4.75K OHM,1%,0.125W,TC=00 PPM	50139	BCK4751FT
A1S120	260-1721-00			SWITCH,ROCKER:8,SPST,125MA,30VDC,	81073	76SB08S
A1S220	260-1721-00			SWITCH,ROCKER:8,SPST,125MA,30VDC,	81073	76SB08S
A1U210	160-7852-00			IC,DIGITAL:CMOS,PAL;PRGM 156-5925-00	80009	160785200
A1U220	160-8061-00			IC,DIGITAL:STTL,PLD'PAL,12L8,5NS,180MA,PRGM	80009	160806100



Replaceable Mechanical Parts

Replaceable Mechanical Parts

This chapter contains a list of the replaceable mechanical components for the TMS 161 80960Cx microprocessor support. Use this list to identify and order replacement parts.

Parts Ordering Information

Replacement parts are available through your local Tektronix field office or representative.

Changes to Tektronix products are sometimes made to accommodate improved components as they become available and to give you the benefit of the latest improvements. Therefore, when ordering parts, it is important to include the following information in your order:

- Part number
- Instrument type or model number
- Instrument serial number
- Instrument modification number, if applicable

If you order a part that has been replaced with a different or improved part, your local Tektronix field office or representative will contact you concerning any change in part number.

Change information, if any, is located at the rear of this manual.

Using the Replaceable Mechanical Parts List

The tabular information in the Replaceable Mechanical Parts List is arranged for quick retrieval. Understanding the structure and features of the list will help you find all of the information you need for ordering replacement parts. The following table describes the content of each column in the parts list.

Parts list column descriptions

Column	Column name	Description
1	Figure & index number	Items in this section are referenced by figure and index numbers to the exploded view illustrations that follow.
2	Tektronix part number	Use this part number when ordering replacement parts from Tektronix.
3 and 4	Serial number	Column three indicates the serial number at which the part was first effective. Column four indicates the serial number at which the part was discontinued. No entries indicates the part is good for all serial numbers.
5	Qty	This indicates the quantity of parts used.
6	Name & description	An item name is separated from the description by a colon (:). Because of space limitations, an item name may sometimes appear as incomplete. Use the U.S. Federal Catalog handbook H6-1 for further item name identification.
7	Mfr. code	This indicates the code of the actual manufacturer of the part.
8	Mfr. part number	This indicates the actual manufacturer's or vendor's part number.

Abbreviations Abbreviations conform to American National Standard ANSI Y1.1-1972.

Chassis Parts Chassis-mounted parts and cable assemblies are located at the end of the Replaceable Electrical Parts List.

Mfr. Code to Manufacturer Cross Index The table titled Manufacturers Cross Index shows codes, names, and addresses of manufacturers or vendors of components listed in the parts list.

Manufacturers cross index

Mfr. code	Manufacturer	Address	City, state, zip code
TK1462	YAMAICHI ELECTRONICS CO LTD 2ND FLOOR NEW KYOEI BLDG 17-11	3-CHROME SHIBAURA MINATO-KU	TOKYO JAPAN
TK2548	XEROX BUSINESS SERVICES DIV OF XEROX CORPORATION	14181 SW MILLIKAN WAY	BEAVERTON OR 97077
53387	3M COMPANY ELECTRONIC PRODUCTS DIV	3M AUSTIN CENTER	AUSTIN TX 78769-2963
63058	MCKENZIE TECHNOLOGY	910 PAGE AVENUE	FREMONT CA 94538
80009	TEKTRONIX INC	14150 SW KARL BRAUN DR PO BOX 500	BEAVERTON OR 97077-0001
81073	GRAYHILL INC	561 HILLGROVE AVE PO BOX 10373	LA GRANGE IL 60525-5914

Replaceable mechanical parts list

Fig. & index number	Tektronix part number	Serial no. effective	Serial no. discont'd	Qty	Name & description	Mfr. code	Mfr. part number
6-0	010-0512-XX			1	ADAPTER,PROBE:92DM17 80960CA PGA 168 SOCKETED	80009	0100512XX
-1	131-5267-XX			3	CONN,HDR:PCB,MALE,STR,2 X 40,0.1 CTR,0.235 MLG X 0.110 TAIL,30 GOLD	53387	2480-6122-TB
-2	136-1134-XX			1	SKT,PL-IN,ELEK:PGA,ZIF;17 X 17,168 PIN	TK1462	NP35-28916-KS11
-3	260-1721-XX			2	SWITCH,ROCKER:8,SPST,125MA,30VDC	81073	76SB08S
-4	671-1973-XX			1	CIRCUIT BD ASSY:80960CX TARGET HEAD;	80009	6711973XX
-5	136-1049-XX			2	SKT,PL-IN ELEK:PGA,16 PIN,17 X 17 VLI,SHORT SOLDER TAIL	63058	PGA168H 101B1 1
STANDARD ACCESSORIES							
	070-9816-00			1	MANUAL,TECH:INSTRUCTION,80960CX,DISSASSEMBLER, TMS 161	80009	070-9816-00
	070-9803-00			1	MANUAL,TECH:TLA 700 SERIES MICRO SUPPORT INSTALLATION	80009	070-9803-00
OPTIONAL ACCESSORIES							
	070-9802-00			1	MANUAL,TECH:BASIC OPS MICRO SUP ON DAS/TLA 500 SERIES LOGIC ANALYZERS	80009	070-9802-00

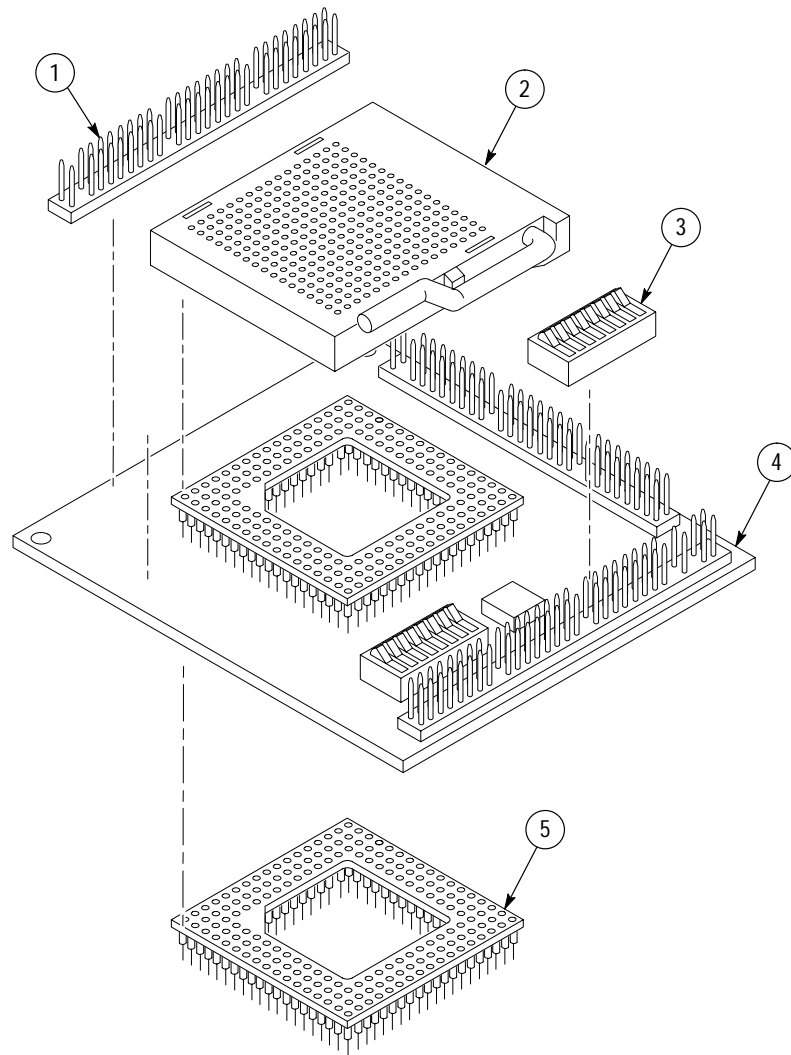


Figure 6-1: Exploded view of probe adapter



Index

Index

A

- A0, A1 addressing signals, 2–12
- about this manual set, ix
- acquiring data, 2–7
- Address group
 - channel assignments, 3–6
 - display column, 2–9
- Alternate Bus Master cycles, 3–13
- alternate connections
 - extra channel probes, 3–14
 - to other signals, 3–14

B

- basic operations, where to find information, ix
- Burst or Burst Pipelineing M0de, 2–12
- bus cycles, displayed cycle types, 2–8
- bus timing, 3–12
- byte ordering, 1–2

C

- certifications, 3–4
- channel assignments
 - Address group, 3–6
 - clocks, 3–10
 - Control group, 3–8
 - Data group, 3–7
 - DataSize group, 3–8
 - Intr group, 3–9
 - Misc group, 3–9
- channel groups, 2–1
- clock channel assignments, 3–10
- clock rate, 1–2
- clocking, Custom, 2–1
 - how data is acquired, 3–11
- clocking options, how data is acquired, 3–13
- compliances, 3–4
- connections
 - no probe adapter, 1–8
 - channel probes, 1–9
 - clock probes, 1–10
 - other microprocessor signals, 3–14
 - probe adapter to SUT, ZIF, 1–5
- Control Flow display format, 2–10
- Control group
 - channel assignments, 3–8
 - display column, 2–9

- Custom clocking, 2–1
 - DMA cycles, 2–1
 - how data is acquired, 3–11
- cycle types, 2–8

D

- data
 - acquiring, 2–7
 - disassembly formats
 - Control Flow, 2–10
 - Hardware, 2–8
 - Software, 2–9
 - Subroutine, 2–11
 - how it is acquired, 3–11
- data display, changing, 2–11
- Data group
 - channel assignments, 3–7
 - display column, 2–9
- DataSize group, channel assignments, 3–8
- demonstration file, 2–13
- dimensions, probe adapter, 3–5
- disassembled data
 - cycle type definitions, 2–8
 - viewing, 2–7
 - viewing an example, 2–13
- disassembler
 - definition, ix
 - logic analyzer configuration, 1–2
 - setup, 2–1
- Disassembly Format Definition overlay, 2–11
- Disassembly property page, 2–11
- display formats
 - Control Flow, 2–10
 - Hardware, 2–8
 - Software, 2–9
 - special characters, 2–7
 - Subroutine, 2–11
- DMA cycles, 2–1

E

electrical specifications, 3–2
environmental specifications, 3–4

H

Hardware display format, 2–8
 cycle type definitions, 2–8
hardware reset, 1–3

I

installing hardware. *See* connections
Intr group, channel assignments, 3–9

L

leads (podlets), ZIF. *See* connections
Little-Endian byte ordering, 1–2
loading, electrical, 1–3
logic analyzer
 configuration for disassembler, 1–2
 software compatibility, 1–2

M

manual
 conventions, ix
 how to use the set, ix
Mark Cycle function, 2–13
Mark Opcode function, 2–13
marking cycles, definition of, 2–13
Memory region assignments, 2–11
microprocessor, specific clocking and how data is
 acquired, 3–11
Misc group, channel assignments, 3–9
Mnemonic display column, 2–9

P

probe adapter
 alternate connections, 3–14
 circuit description, 4–1
 clearance, 1–5
 adding sockets, 1–7

 dimensions, 3–5
 configuring, 1–3, 3–1
 electrical loading, 1–3
 hardware description, 3–1
 jumper positions, 3–1
 not using one, 1–8
 placing the microprocessor in, ZIF, 1–7

R

reference memory, 2–13
reset, hardware, 1–3
restrictions, 1–2
 without a probe adapter, 1–8

S

service information, 4–1
setups, disassembler, 2–1
signals
 active low sign, x
 alternate connections, 3–14
 extra channel probes, 3–14
Software display format, 2–9
special characters displayed, 2–7
specifications, 3–1
 certifications, 3–4
 channel assignments, 3–5
 compliances, 3–4
 electrical, 3–2
 environmental, 3–4
 mechanical (dimensions), 3–5
Subroutine display format, 2–11
support setup, 2–1
SUT, definition, ix
synthesized signals, 3–13

T

terminology, ix
Timestamp display column, 2–9

V

viewing disassembled data, 2–7

